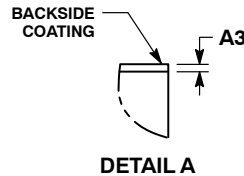
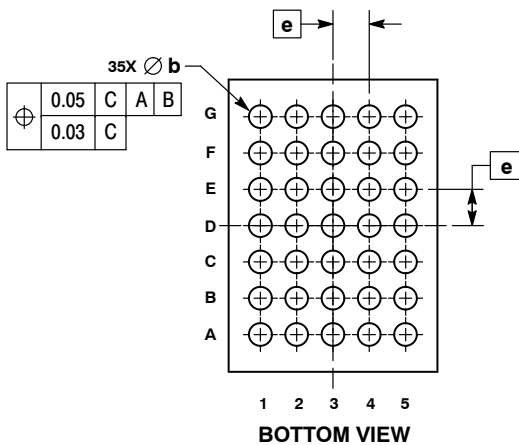
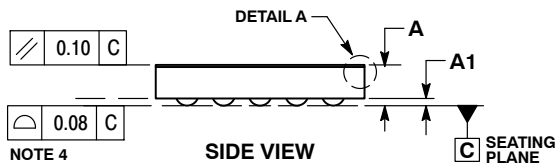
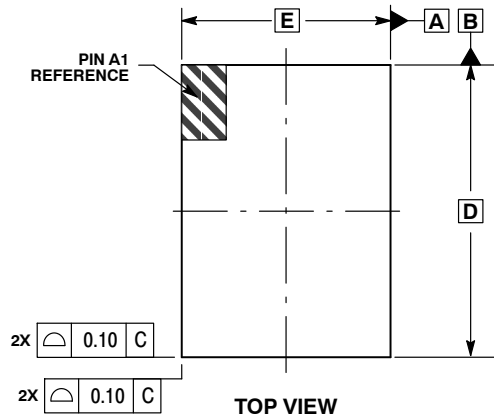


SCALE 4:1

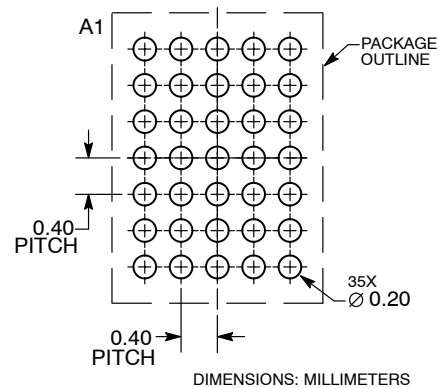
WLCSP35, 3.22x2.3
CASE 567LJ
ISSUE B

DATE 17 MAR 2017


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.35	0.45
A1	0.03	0.13
A3	0.025	REF
b	0.15	0.25
D	3.22	BSC
E	2.30	BSC
e	0.40	BSC

RECOMMENDED SOLDERING FOOTPRINT*


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP35, 3.22X2.3	PAGE 1 OF 1

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